



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Blaine J. Thurgood

**Serial No.:** 10/787,351

**Filed:** February 26, 2004

**For:** SEMICONDUCTOR DIE  
CONFIGURED FOR USE WITH  
INTERPOSER SUBSTRATES HAVING  
REINFORCED INTERCONNECT SLOTS

**Confirmation No.:** 4866

**Examiner:** J. Clark

**Group Art Unit:** 2815

**Attorney Docket No.:** 2269-5520.2US  
(02-0676.02/US)

**Notice of Allowance Mailed:**

January 6, 2006

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL995990041US

Date of Deposit with USPS: April 4, 2006

Person making Deposit: Timothy Palfreyman

OK to enter  
gpc  
04/17/06

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows: